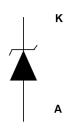




15 V, 25 A unidirectional TVS in SOD882T





Unidirectional

Product status link

ESDA17P20-1F2

Features

Peak pulse power: 600 W (8/20 µs)

Stand-off voltage: 15 V

Unidirectional type

Low leakage current: 80 nA at 25 °C

Operating T_i max: 150 °C

Lead finishing: gold

Complies with the following standards

- IPC7531 footprint and JEDEC registered package outline
- IEC 61000-4-2, C = 150 pF R = 330 Ω exceeds level 4:
 - 30 kV (contact discharge)
 - 30 kV (air discharge)

Description

The ESDA17P20-1F2 is a unidirectional single line TVS diode designed to protect the power line against EOS and ESD transients.

The device is ideal for applications where board space saving is required.



1 Characteristics

Table 1. Absolute maximum ratings (T_{amb} = 25 °C)

Symbol		Value	Unit	
V _{pp}	Peak pulse voltage ISO10605 (C = 330 pF, R = 330 Ω) contact discharge air discharge		30 30	kV
P _{pp}	Peak pulse power (8/20 μs)		600	W
I _{pp}	Peak pulse current (8/20 μs)	25	Α	
T _{op}	Operating junction temperatur	-55 to 150		
T _{stg}	Storage junction temperature	-55 to 150	°C	
TL	Maximum lead temperature fo	260		

Figure 1. Electrical characteristics (definitions)

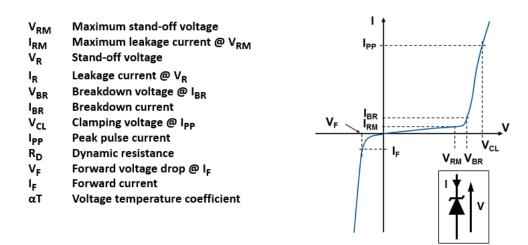


Table 2. Electrical characteristics (values) (T_{amb} = 25° C)

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
V _{RM}	Stand-off voltage				15	V
V _{BR}	Breakdown voltage	I _R = 1 mA	15.6	16.7	17.9	V
I _{RM}	Leakage current	V _{RM} = 15 V			80	nA
		I _{pp} = 20 A - 8/20 μs			23	
V _{CL} Clamping voltage	IEC 61000-4-2, 8 kV contact discharge measured at 30 ns		20.6		V	
R _D	Dynamic resistance, pulse	8/20 µs		0.25		Ω
C _{LINE}	Line capacitance	f = 1 MHz, V _{LINE} = 0 V, V _{OSC} = 30 mV		190		pF

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1.1 Characteristics (curves)

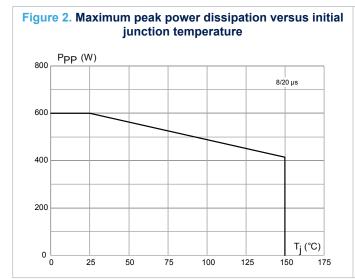


Figure 3. Maximum peak pulse power versus exponential pulse duration

PPP (W)

T_i initial = 25 °C

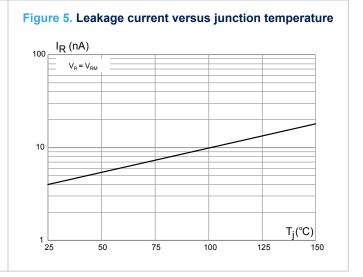
T_i initial = 25 °C

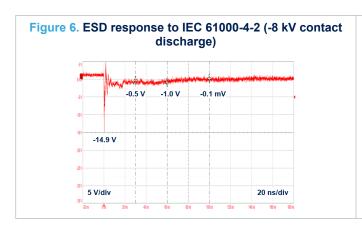
100

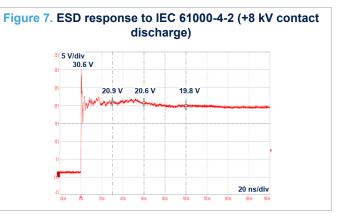
100

100

1000







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2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SOD882T package information

Figure 8. SOD882T package outline

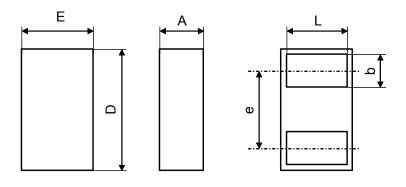


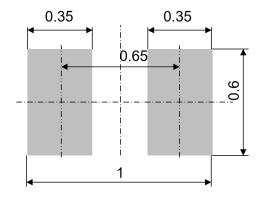
Table 3. SOD882T mechanical data

	Dimensions					
Ref.	Millimeters					
	Min.	Тур.	Max.			
Α	0.330	0.350	0.370			
b	0.230	0.250	0.270			
D	0.970	1.000	1.030			
E	0.570	0.600	0.630			
е		0.650				
L	0.480	0.500	0.520			

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Figure 9. Recommended footprint (mm)



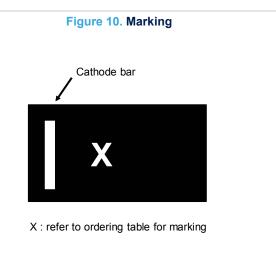
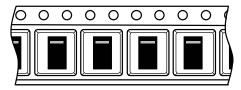


Figure 11. Package orientation in reel



Taped according to EIA-481

Note: Pocket dimensions are not on scale Pocket shape may vary depending on package On bidirectional devices, marking and logo may be not always in the same direction

Figure 12. Tape and reel orientation

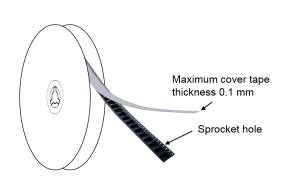


Figure 13. Reel dimension values (mm)

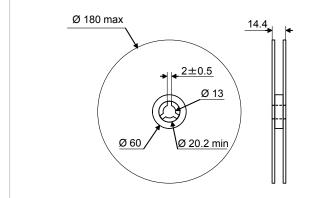
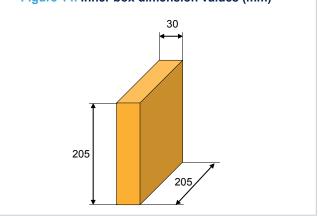


Figure 14. Inner box dimension values (mm)



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W P1 P2 Ø D1

User direction of unreeling

Figure 15. Tape outline

Note: Pocket dimensions are not on scale Pocket shape may vary depending on package

Table 4. Tape dimension values

	Dimensions					
Ref.	Millimeters					
	Min.	Тур.	Max.			
D0	1.5	1.55	1.6			
D1	0.195	0.2	0.205			
F	3.45	3.5	3.55			
K0	0.39	0.42	0.45			
P0	3.9	4.0	4.1			
P1	1.95	2.0	2.05			
P2	1.95	2.0	2.05			
W	7.9	8.0	8.3			

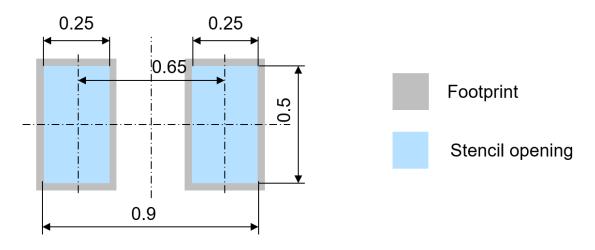
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3 PCB assembly recommendations

3.1 Recommended stencil opening

Figure 16. Recommended stencil opening (mm)



Stencil opening thickness: 100 µm

3.2 Solder paste

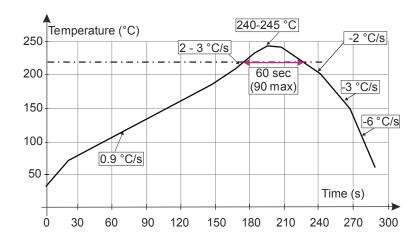
- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Use solder paste with fine particles: powder particle size 20-38 μm.

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3.3 Reflow profile

Figure 17. ST ECOPACK® recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

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4 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
ESDA17P20-1F2	Α	SOD882T	0.54 mg	10000	Tape and reel

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Revision history

Table 6. Document revision history

Date	Version	Changes
15-Jun-2020	1	Initial release.

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